

IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

Claims 1 - 24 (cancelled)

25. (previously amended) A manufacturing method for a solder coated material comprising electroplating a difficult to solder material with a material having excellent solderability to form an electroplated layer, and then passing the difficult to solder material through a molten solder bath to form a hot dip solder plating layer having a thickness of 10 - 50 micrometers on the electroplated layer.

26. (previously added) A manufacturing method for a solder coated material as claimed in claim 25 including applying ultrasonic waves to the molten solder bath.

27. (previously added) A manufacturing method for a solder coated material as claimed in claim 25 wherein the difficult to solder material is an iron-nickel alloy.

28. (previously added) A manufacturing method for a solder coated material as claimed in claim 25 wherein the material having excellent solderability is selected from gold, silver, copper, tin, nickel, and solder alloys.

29. (previously added) A manufacturing method for a solder coated material as claimed in claim 25 wherein the molten solder bath is maintained in an inert atmosphere.

30. (previously added) A manufacturing method for a solder coated material as claimed in claim 25 wherein the molten solder bath in the molten solder is a wave soldering bath.

Claim 31 (cancelled)

32. (currently amended) ~~A portion to be soldered of an electronic part as claimed in claim 20 wherein the portion to be soldered is a~~ battery terminal comprising a substrate comprising a difficult to solder material, an electroplated layer of a material having excellent solderability and having a thickness of 0.5 - 5 micrometers applied as base plating atop the substrate, and a hot dip solder plating layer with a thickness of 10 - 50 micrometers applied atop the electroplated layer.

33. (currently amended) ~~A portion to be soldered of an electronic part as claimed in claim 20 wherein the portion to be soldered is a~~ shield of a module comprising a substrate comprising a difficult to solder material, an electroplated layer of a material having excellent solderability and having a thickness of 0.5 - 5 micrometers applied as base plating atop the substrate, and a hot dip solder plating layer with a thickness of 10 - 50 micrometers applied atop the electroplated layer.

Claim 34 (cancelled)

35. (previously added) A method as claimed in claim 25 wherein the difficult to solder material forms part of a lead frame for an electronic part.

36. (previously added) A method as claimed in claim 25 wherein the difficult to solder material forms part of a lid of a packaged electronic part.

37. (previously added) A method as claimed in claim 25 wherein the difficult to solder material forms part of a battery terminal.

38. (previously added) A method as claimed in claim 25 wherein the difficult to solder material forms a part of a shield of a module.

39. (previously added) A method as claimed in claim 25 wherein the difficult to solder material forms part of a connector for a surface mounted part.

40. (previously added) A method as claimed in claim 25 wherein the hot dip solder plating layer has a thickness of 15 - 40 micrometers.

41. (previously added) A method of forming a packaged

electronic part comprising performing reflow soldering of a lid including a substrate of a difficult to solder material, an electroplated layer of a material having excellent solderability formed on the substrate as base plating, and a hot dip solder plating layer formed on the electroplated layer to a package to join the lid to the package.

42. (previously added) A method as claimed in claim 41 wherein the electroplated layer has a thickness of 0.5 - 5 micrometers and the hot dip solder plating layer has a thickness of 10 - 50 micrometers.

Claim 43 (cancelled, and re-presented as claim 53)

Claim 44 (cancelled)

45. (previously added) A method as claimed in claim 36 wherein the hot dip solder plating layer has a thickness of 15 - 40 micrometers, and the electroplated layer and the hot dip solder plating layer are formed on one but not both of a top and a bottom side of the lid.

46. (previously added) A method as claimed in claim 36 wherein the difficult to solder material is an iron-nickel alloy, and the electroplated layer and the hot dip solder plating layer are formed on one but not both of a top and a bottom side of the lid.

47. (previously added) A method as claimed in claim 42 wherein the hot dip solder plating layer has a thickness of 15 - 40 micrometers, and the electroplated layer and the hot dip solder plating layer are formed on one but not both of a top and a bottom side of the lid.

48. (previously added) A method as claimed in claim 42 wherein the difficult to solder material is an iron-nickel alloy, and the electroplated layer and the hot dip solder plating layer are formed on one but not both of a top and a bottom side of the lid.

49. (previously added) A method as claimed in claim 25 wherein the difficult to solder material comprises a continuous plate, the method including:

forming the electroplated layer and the hot dip solder plating layer on one but not both of a top and a bottom side of the continuous plate; and

punching the continuous plate after forming the hot dip solder plating layer to obtain preplated parts.

50. (previously added) A method as claimed in claim 49 including punching the plate to form preplated lids for semiconductor packages.

51. (previously added) A method as claimed in claim 49 wherein the hot dip solder plating layer has a thickness of 15 -

40 micrometers.

52. (previously added) A method as claimed in claim 49 wherein the plate comprises an iron-nickel alloy.

53. (re-presented - formerly dependent claim 43) A lid of a packaged electronic part comprising a substrate comprising a difficult to solder material, an electroplated layer of a material having excellent solderability and having a thickness of 0.5 - 5 micrometers applied as base plating atop the substrate, and a hot dip solder plating layer with a thickness of 15 - 40 micrometers applied atop the electroplated layer, the electroplated layer and the hot dip solder plating layer being formed on one but not both of a top and a bottom side of the lid.

54. (new) A lid as claimed in claim 53 wherein the substrate is an iron-nickel alloy.